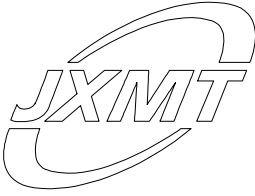
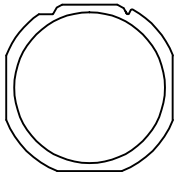
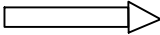
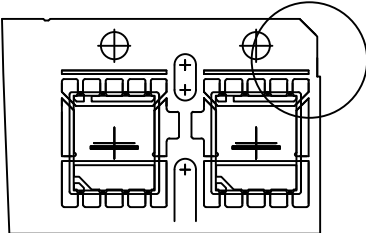
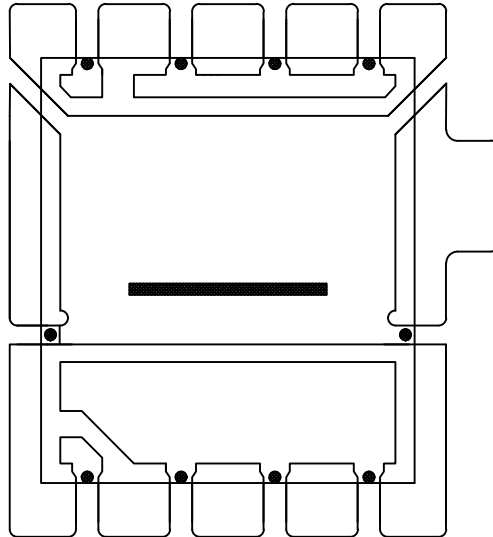


Bonding Diagram

| | | | | | |
|--|---|--|---------|-------------|----------|
|  | 安徽积芯微电子科技有限公司 Anhui Jixin Microelectronics Technology Ltd. | | | | |
| | BD No. | | 版本 | | |
| | Device | | Package | PDFN5X6B | Customer |
| 装片方向  | 引线框传输方向  |  | | 客户确认 | |



| BOM | TYPE | | | | | |
|----------------------------|--|-----------------------------|-------------------------|----------------------|--|------------------------------|
| | Die Name | Wafer Size (inch) | Die Size Without SL(μm) | Gate Pad Size (μm) | Scribe Line (μm) | Die Thickness (μm) |
| 芯片CHIP | | | | | | |
| 引线框物料号 L/F Material No: | | 栅极线材规格 Gate Wire Spec. | | 银胶 Epoxy | | 晶圆背金 Wafer back material |
| 基岛尺寸 (mm) L/F Pad Size | CH1:4.530 * 1.370 CH2:4.530 * 2.273 | 源极线材规格 Source Wire Spec. | | 锡膏 Solder paste | | |
| 电镀方式 L/F Plating Type | | 总线数 Total Qt'y | | 塑封料 Compound | | 晶圆正面金属 Wafer top material |
| 焊线方式 Wire Type | | 产品等级 MSL Level | | 电镀方式 Plating Type | | |
| 线图来源 BD source | | | | 备注 Remark | | |
| 制图日期 | | | | 有效期 | <input type="checkbox"/> 永久 <input type="checkbox"/> 六个月 <input type="checkbox"/> 其他 | |
| 拟制 Prepared By | | 审核 Checked By | | 批准 Approved By | | 文控发行章 Controlled Chapter |